



MASTER BUILDERS ASSOCIATION MALAYSIA PERSATUAN KONTRAKTOR BINAAN MALAYSIA

(PPM-002-14-26051954)

*The Prime Mover and The Recognised Voice
of the Malaysian Construction Industry*



Council for 2016 - 2018

President

Foo Chek Lee JMW
Pembinaan Mirajaya Sdn Bhd

Immediate Past President

Datuk Matthew Tee Kai Woon DPSM
Bina Puri Sdn Bhd

Deputy President

Tan Sri Dato' A.K. Nathan Elumalay PSM, DSNs
Eversendai Constructions (M) Sdn Bhd

Vice President

Tan Sri Dato' Sri Sufti Hj. Mohd Zin
PSM, SSAP, DPTJ
Trans Resources Corporation Sdn Bhd

Liew Hau Seng

LJM Corporation Berhad

Ir. Chuan Yeong Ming MIE, PEng
Tim Sekata Sdn Bhd

Chung Soo Kiong

Sunway Construction Sdn Bhd

Oliver Wee Hing Chyn AMN
Pasukan Khas Construction Sdn Bhd

Secretary-General

Dennis Tan Soo Huang
Ocened Water Technology Sdn Bhd

Deputy Secretary-General

Ong Ka Thiam
WCT Berhad

Eric Yong Shang Ming

Crest Builder Sdn Bhd

Treasurer-General

Kenneth Liew Kiam Woon
LFE Engineering Sdn Bhd

Council Member

Mohd Razin Bin Ghazali
Ahmad Zaki Sdn Bhd

Chong Tat Yam

Al-Ambia Sdn Bhd

Ir. Au Yong Yoke Lin

Bauer (Malaysia) Sdn Bhd

Png Choon Yam

Bina Puri Sdn Bhd

Eric Kuan Khian Leng

Fajarbaru Builder Sdn Bhd

Dato' Ubull Din Om DIMP

Gamuda Bhd

Ang Wei Zhen

Ikimas Jaya Sdn Bhd

Lau Yew Mun

Ireka Corporation Berhad

Ir. James Wong Tet Foh

Mudajaya Corporation Berhad

Datuk Astaman Abdul Aziz DMSM

Norwest Holdings Sdn Bhd

Dato' Steven Hooi Kok Hoe DIMP

Premier Construction Sdn Bhd

Fong Tet Young

Rooframes Resources Sdn Bhd

Michael Yap Kok Wai

Satujaya Sdn Bhd

Kow Choong Ming

Senia Precast Sdn Bhd

Yeoh Keong Yuan

Syarikat Pembinaan Yeoh Tiong Lay Sdn Bhd

Tan Zi Ni

Trans Elite Group Sdn Bhd

Nalla Sundran

VSL Engineers (M) Sdn Bhd

Honorary Members

Honorary Life Presidents

Tan Sri Dato' Seri (Dr) Yeoh Tiong Lay
PSM, SPMS, SPDK, DPMS, KMN, FPN, PJK
Syarikat Pembinaan Yeoh Tiong Lay Sdn Bhd

Datuk Lai Fook Kong P.J.N. JSM

Ireka Corporation Bhd

Tan Sri Dato' Low Keng Huat

PSM, SIMP, DIMP, DKBS
Low Keng Huat Bhd

Honorary Builder

Ir. Lau Mun Cheong JMN, KMN

Sekimas Holdings Sdn Bhd

Honorary Advisors

Ir. Lau Mun Cheong JMN, KMN

Sekimas Holdings Sdn Bhd

Dato' Ir. Tan Kia Loke

DSNS, JMN, AMN, AMT, PJK
Sunway Group

Dato' Ng Kee Leen DIMP, KMN

Peridot Development Sdn Bhd

Datuk Kwan Foh Kwai P.J.N. JMN, JMW

Sunway Construction Group Berhad

Honorary Advisor (Legal)

John Tong

Messrs John Tong, Fahmi & KH Yeoh

Honorary Advisor (Education)

Chua Siow Leng KMN

Honorary Advisor (Taxation)

Yee Wing Peng

Deloitte Tax Services Sdn Bhd

Website

mbam.org.my

MBAM/25/01/431/2018-04-10/014

10 April 2018

TO: ALL MEMBERS (INVITATION TO PARTICIPATE)

RE: 9TH INTERNATIONAL INFRASTRUCTURE INVESTMENT & CONSTRUCTION FORUM (IIICF)
7-8 JUNE 2018 AT VENETIAN HOTEL MACAO, SAR, CHINA

IIICF is an international forum with the theme of investment and construction of infrastructure, which was founded in 2010 by CHINCA with the approval of the Chinese Ministry of Commerce. The Forum serves as a platform of communication, exchange and cooperation where interested parties discuss about hot topics and development strategies of international infrastructure investment and construction to promote mutually beneficial cooperation. The Forum has been successfully held six times in Beijing and Macao and have attracted more than 8,000 delegates from nearly 100 countries and international organisations.

The theme of the 9th IIICF is "Fostering New Drivers of Development to Boost Infrastructure Construction and Connectivity". Currently, a new wave of technical revolution and industrial transformation is experiencing rapid development. Led by technological innovation, the new drivers of economic development are coming into being. How will the emergence of new drivers affect international infrastructure development and how to foster new drivers that are conducive to the sustainable infrastructure development? How will the international industry adapt to the transformation of the drivers of the global economy and make full use of the new drivers to solve problems facing the industry?

This year, they will be issuing a brochure of project information that will be furnished by various organizations, multilateral development institutes, banks, international associations, trade & investment agencies, etc. Thus, companies that wish to seek cooperation in projects (not limited to infrastructure projects) are to complete the attached project information form and email to mbam08@mbam.org.my. The information will be release at 9th IIICF and it is "to make the Forum a more effective platform for information sharing, business matching, and project landing."

We invite your esteem organisation to join MBAM delegation to attend in this Forum as the participation fee is **FREE**. Members who are interested to participate are requested to complete the reply slip below and email to MBAM Secretariat on/before **Monday, 07 May 2018**. A copy of the forum details is enclosed for your easy reference. Please note that the air ticket and hotel accommodation are to be borne by the participants. The official hotel is Venetian Hotel Macao SAR, CHINA

Thank you and we look forward to your kind support and participation.

Yours faithfully,

MASTER BUILDERS ASSOCIATION MALAYSIA


LOH MEI LING
Executive Director

No. 2-1, Jalan 2/109E, Desa Business Park, 58100 Kuala Lumpur, Wilayah Persekutuan Kuala Lumpur.
Tel: +603-7984 8636 e-mail: ed@mbam.org.my Fax: +603-7982 6811/9811 GST ID No: 001267208192
Regular Member: International Federation of Asian & Western Pacific Contractors' Associations (IFAWPCA)
Founder Member: ASEAN Constructors' Federation (ACF)
44th IFAWPCA Convention Website: ifawpca2018.my



Certified to ISO 9001:2008
Cert. No: AR 1824





REPLY SLIP

(Please email to mbam08@mbam.org.my/ fax to 03-79826811 on/before Monday, 07 May 2018)

Yes, the following are interested to participate in the 9th IIICF, Macao SAR, China held on 07-08 June 2018.

No.	Name	Designation	Email	Mobile No.
1				
2				
3				
4				
5				

Company Name : _____

Contact Person : _____

Email : _____ Tel : _____

Signature : _____